

SCOPE OF ACCREDITATION

Electronics - Printed Board Assemblies

Zollner Elektronik AG / Plant Untergschwandt
Untergschwandt 3
Rattenberg, 94371
Germany

This certificate expiration is updated based on periodic audits. The current expiration date and scope of accreditation are listed at: www.eAuditNet.com - Online QML (Qualified Manufacturer Listing).

In recognition of the successful completion of the PRI evaluation process, accreditation is granted to this facility to perform the following:

AC7000 - AUDIT CRITERIA FOR NADCAP ACCREDITATION

AC7120 Rev E - Nadcap Audit Criteria for Printed Board Assemblies (to be used on audits on/after 9 April 2017) (CANNOT BE COMBINED WITH AC7119 or AC7121)

- 03–Company Information (mandatory)
- 04– General (mandatory)
- 05– Outsourced Processes (mandatory)
- 06– Process Control (mandatory)
- 07– Visual Acuity (mandatory)
- 08– Customer Data (mandatory)
- 09– Electrostatic Discharge (ESD) (mandatory)
- 10– Material Management (mandatory)
- 11– Moisture Sensitive Components and Materials
- 12– Kitting
- 13.1– In–Process Verification / Inspection: General (mandatory)
- 13.2– In–Process Verification / Inspection: Visual (mandatory)
- 13.3– In–Process Verification / Inspection: AOI
- 14.1– Secondary Assembly: Mechanical Part Installation
- 14.6– Secondary Assembly: Bonding
- 15– Cleanliness
- 16– Final Inspection (mandatory)
- 17– Rework (mandatory)

AC7120/2 - General Soldering of Printed Board Assemblies (to be used on audits on/after 9 April 2017)

- 03– General (mandatory)
- 04– Electronic Component Preparation for Preassembly Process
- 05.1– Part Placement: General (mandatory)

- 05.2– Part Placement: Manual
- 06– Gold Removal
- 07– Build Through / Build Short
- 08– Hand Soldering

AC7120/3 - Plated Through Hole Technology (to be used on audits on/after 9 April 2017)

- 05– Selective Soldering

AC7120/4 Rev A - Surface Mount Technology (to be used on audits on/after 3 March 2019)

- 03– Preparation
- 04– Stencil Printing (mandatory)
- 05– Automated Part Placement (mandatory)
- 06– Reflow Soldering (mandatory)

AC7120/7 - Conformal Coating of Printed Board Assemblies (to be used on audits on/after 9 April 2017)

- 04– Material (mandatory)
- 05– Material and Equipment Compatibility (mandatory)
- 06– Preparation / Cleaning (mandatory)
- 07– Application / Drying / Curing (mandatory)
- 08– Thickness (mandatory)
- 09– Inspection (mandatory)
- 10– Rework (mandatory)
- 11– Training (mandatory)

AC7120/9 - Programming (to be used on audits on/after 9 April 2017)

- 04– General (mandatory)
- 06– Circuit Card Assembly Programming

AC7120/10 - Final Testing (to be used on audits on/after 9 April 2017)

- 04– General

AC7120/12 - Nadcap Audit Criteria for Depaneling (to be used on audits on/after 30 June 2019)

- 02– Inspection (mandatory)
- 03– Mechanical Router Process
- 08– Pizza Cutter ('V' Groove Depanelizer)
- 11– Preservation and Packing of Depaneled Images (mandatory)